

# **2021 International Symposium on VLSI Design, Automation and Test (VLSI-DAT 2021)**

**Hsinchu, Taiwan  
19 – 22 April 2021**



**IEEE Catalog Number: CFP21847-POD  
ISBN: 978-1-6654-3028-9**

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IEEE Catalog Number:	CFP21847-POD
ISBN (Print-On-Demand):	978-1-6654-3028-9
ISBN (Online):	978-1-6654-1915-4
ISSN:	2380-7369

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